

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5289140

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BAOQUAN WU	12/07/2018
WEI LONG	12/07/2018
YUPING LIU	12/10/2018
RECEIVING PARTY DATA	
Name:	SHENZHEN GOODIX TECHNOLOGY CO., LTD.
Street Address:	FLOOR 13, PHASE B, TENGFEI INDUSTRIAL BUILDING
Internal Address:	FUTIAN FREE TRADE ZONE
City:	SHENZHEN, GUANGDONG
State/Country:	CHINA
Postal Code:	518045
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16139994
CORRESPONDENCE DATA	
Fax Number:	(518)452-5579
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	518-452-5600
Email:	noreen.pettalino@hrfmlaw.com
Correspondent Name:	JEFF ROTHENBERG, ESQ.
Address Line 1:	HESLIN ROTHENBERG FARLEY & MESITI P.C.
Address Line 2:	5 COLUMBIA CIRCLE
Address Line 4:	ALBANY, NEW YORK 12203
ATTORNEY DOCKET NUMBER:	5232.087
NAME OF SUBMITTER:	JEFF ROTHENBERG
SIGNATURE:	/JEFF ROTHENBERG/
DATE SIGNED:	12/18/2018
Total Attachments: 3	
source=H1355755#page1.tif	
source=H1355755#page2.tif	

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNOR:

WU, Baoquan

Floor 13, Phase B, Tengfei Industrial Building, Futian Free Trade Zone
Shenzhen, Guangdong 518045 China

hereby sells, assigns and transfers to ASSIGNEE:

SHENZHEN GOODIX TECHNOLOGY CO., LTD.

Floor 13, Phase B, Tengfei Industrial Building, Futian Free Trade Zone
Shenzhen, Guangdong 518045 China

and the successors, assigns and legal representatives of the ASSIGNEE the entire rights, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the Application entitled:

**SECONDARY PACKAGING METHOD AND SECONDARY PACKAGE OF THROUGH
SILICON VIA CHIP**

which application was executed by the undersigned on even date herewith

and, in and to all Letters patent to be obtained for said invention by the above application on any continuation, divisional, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known as accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year:

WU Baoquan
WU, Baoquan

2018/12/07
Date

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNOR:

LONG, Wei

Floor 13, Phase B, Tengfei Industrial Building, Futian Free Trade Zone
Shenzhen, Guangdong 518045 China

hereby sells, assigns and transfers to ASSIGNEE:

SHENZHEN GOODIX TECHNOLOGY CO., LTD.

Floor 13, Phase B, Tengfei Industrial Building, Futian Free Trade Zone
Shenzhen, Guangdong 518045 China

and the successors, assigns and legal representatives of the ASSIGNEE the entire rights, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the Application entitled:

SECONDARY PACKAGING METHOD AND SECONDARY PACKAGE OF THROUGH SILICON VIA CHIP

which application was executed by the undersigned on even date herewith

and, in and to all Letters patent to be obtained for said invention by the above application on any continuation, divisional, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known as accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year:

Long Wei
LONG, Wei

2018/12/7
Date

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNOR:

LIU, Yuping

Floor 13, Phase B, Tengfei Industrial Building, Futian Free Trade Zone
Shenzhen, Guangdong 518045 China

hereby sells, assigns and transfers to ASSIGNEE:

SHENZHEN GOODIX TECHNOLOGY CO., LTD.

Floor 13, Phase B, Tengfei Industrial Building, Futian Free Trade Zone
Shenzhen, Guangdong 518045 China

and the successors, assigns and legal representatives of the ASSIGNEE the entire rights, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the Application entitled:

SECONDARY PACKAGING METHOD AND SECONDARY PACKAGE OF THROUGH SILICON VIA CHIP

which application was executed by the undersigned on even date herewith

and, in and to all Letters patent to be obtained for said invention by the above application on any continuation, divisional, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known as accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year:

Liu Yuping
LIU, Yuping

2018.12.10
Date

(N1541176.1)